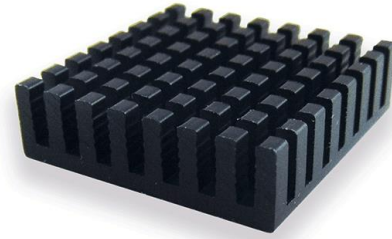


Product Data Sheet Type: PG2828/8/SE/SF

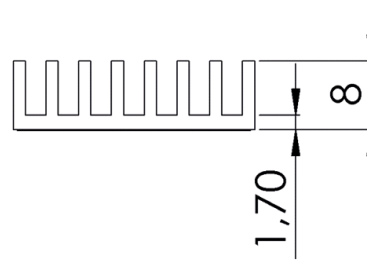
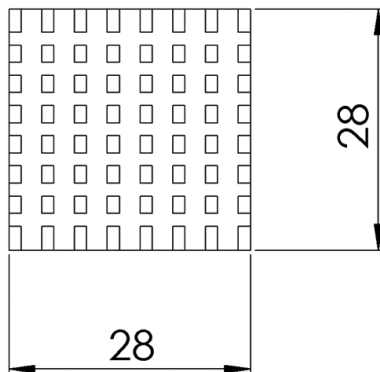
Group: HEATSINKS Board Level

For single mounting

Width : 28 mm
Height : 8 mm
Length : 28 mm
Minimum thermal resistance : 11 K/W
For device : PGA|BGA|IC
Device mounted by :
Heatsink mounted by :
Surface :
Material : AlMgSi0,5



- Heatsinks for microprocessors (Extrusion Technology)
- Direct mounting with self-adhesive foil
- Best possible heat radiation from black anodized surface
- RthKvalues apply to natural convection (without external ventilation)
- Arrangement and number of pins for optimal air flow
- Even heat distribution in the base and the pins in the direction of heat flow
- Suitable for forced and free convection
- Aluminium alloy Al MgSi 0.5
- Thermal conductivity: 180-200 W / mK
- Other dimensions and surface finishes by request



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